

USPTO Serial No. 93,671 (Docket No. ISOT-020)

Amendments to the Specification: (strikethrough parts deleted and underlined parts added)

On page 17, first paragraph, please enter the following amendment:

The thermally conditioned liquid coolant is directly applied to the electronic device 16 within the chamber 50. After the liquid coolant is heated (or cooled) from the electronic device 16, the waste coolant is then returned to the liquid thermal management system 60 for thermal conditioning and cleaning. It can be appreciated that the above method of use can be utilized in conjunction with pin grid arrays, ball grid arrays, land grid arrays and other connection systems.